A 312 ps response-time LDO with enhanced super source follower in 28 nm CMOS

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High quality fully integrated power supplies could notably improve the performances of the noise-sensitive building block in the UWB communication systems. Double buffers are inserted into the cascode flipped-voltage-follower (FVF) topology to enable designing the dominant pole at the output node for better power supply rejection (PSR) and less voltage variation during load transient. An enhanced super source follower (E-SSF) is proposed to further reduce the output impedance of the buffer that drives the power transistor. The FVF-based low dropout regulator (LDO) with E-SSF achieves a worst-case PSR of $-18.9~\mathrm{dB}$ across the full spectrum and a transient response time of 312 ps. The proposed LDO is designed in a 28 nm CMOS process and consumes $100~\mu\mathrm{A}$ quiescent current with $1.0~\mathrm{V}$ input and $0.8~\mathrm{V}$ output voltages. In total, $120~\mathrm{pF}$ on-chip capacitors are used for filtering.

Introduction: Power supply rejection (PSR) is one of the most important specifications for a low dropout regulator (commonly known as LDO). In particular, wideband or even full-spectrum PSR is in demand for the UWB wireless/wireline communication systems [1, 2]. In these applications, filtering capacitors have to be on-chip, in order to eliminate the bond-wire effects and to reduce the on-chip coupled supply noises [2]. Moreover, minimising the number of off-chip components can shrink the device size and reduce the cost.

Flipped-voltage-follower (FVF) [3]-based LDO is one of the most popular architectures [4, 5], due to its simplicity and the potential for fast-transient-response. Since the FVF-based LDO is a single-ended topology, for a similar dynamic response, the FVF-based LDO only consumes 50% of the bias current compared with a conventional LDO that uses a differential error amplifier (EA). Although the FVF-based LDO also consists of an auxiliary differential EA, it is not in the main loop, and only serves as a bias voltage generator which consumes low current. Thus, the FVF-based LDO is more power-efficient.

The FVF with folded-cascode gain stage used in [4] and [5] can provide better DC regulation but makes it more difficult to drive large capacitive load for stability reasons. The FVF with a buffer stage designed in [1] is a low-gain but high bandwidth loop, achieving a full-spectrum worst-case PSR of -12 dB and a fast response time of 0.65 ns. The design of Zhan and Ki [6] demonstrated a full-load worst-case PSR of -38 dB with cascoded power transistors and a dropout voltage of 600 mV, sacrificing the efficiency and the transient performance. In this design, a full-spectrum worst-case PSR of -18.9 dB is achieved for UWB wireline/wireless receivers, with 200 mV dropout voltage and 100 pF load capacitor. In addition, the designed LDO has subnanosecond transient response time, making it suitable for digital loads as well.

Circuit implementation: As illustrated in Fig. 1b, the frequency of the output pole $p_{\rm OUT}$ shifts with load conditions. Besides, the load capacitor $C_{\rm L}$ includes the parasitic capacitors, like the n-well/p-sub junction capacitors and the gate capacitors of the load circuit, which means $p_{\rm OUT}$ could be an unavoidable low-frequency pole, Therefore, designing the dominant pole at the output node can achieve higher unity gain frequency (UGF), compared with the case that designs the $p_{\rm OUT}$ as a non-dominant pole. In addition, allocating most of the available on-chip capacitance (chip area) to the output node can reduce the instant voltage droop during load transient, and can also better filter out the input voltage ripples. The only drawback is that more current is needed to push the internal poles to the frequencies higher than the UGF. However, this problem will be alleviated in more advanced processes, making this process scalable LDO favourable for high performance designs.

Since the cascode FVF topology provides higher DC loop gain and consequently higher UGF, it is more difficult to make the loop being stable, especially when the UGF is in the ultra-high-frequency (UHF) band. As shown in Fig. 1a, in this Letter, double-buffers are inserted to drive the power transistor $M_{\rm P}$, and only add tiny load capacitance to the node $V_{\rm A2}$. The first buffer $B_{\rm 1}$ is simply an N-type metal–oxide–semiconductor (NMOS) source follower, while the second one $B_{\rm 2}$ is

an enhanced super source follower (E-SSF) which is first proposed in this Letter.

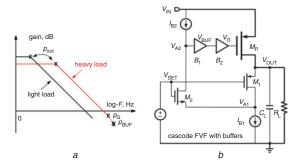


Fig. 1 Schematic of FVF-based LDO with two buffer stages and locations of poles in conceptual Bode plot

- a Schematic of cascode FVF with buffers
- $b\,$ Conceptual Bode plot of open-loop transfer function

The transistor-level schematic of the proposed LDO is given in Fig. 2. $V_{\rm OUT}$ is a mirrored voltage of $V_{\rm MIR}$, both of which are one $V_{\rm GS}$ higher than $V_{\rm SET}$. The function of the left part is to generate the bias voltage $V_{\rm SET}$. In the reference circuit design, the $V_{\rm REF}$ is commonly generated by conducting a current through a resistor. When the $V_{\rm REF}$ is close to its supply voltage $V_{\rm IN}$, there is not enough voltage headroom for an accurate current source, such that the accuracy of the $V_{\rm REF}$ will be degraded. For using a lower reference voltage $V_{\rm REF}$, a resistor ladder of R_1 and R_2 is employed to divide $V_{\rm MIR}$ and feed it back to the EA differential input.

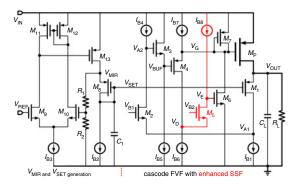


Fig. 2 Schematic of proposed LDO

The right part of the schematic shows the core circuits of the FVF structure with the proposed E-SSF. M_1 and M_2 serve as two commongate amplification stages that provide the DC gain. M_3 is an NMOS source follower providing low input capacitance to the $V_{\rm A2}$ node, and also shifts down the voltage of $V_{\rm A2}$ into $V_{\rm BUF}$ providing more voltage headroom for $V_{\rm G}$. To effectively drive $M_{\rm P}$, a smaller output impedance of the SSF is needed. In the conventional SSF, only M_4 and M_6 are used, while in the proposed E-SSF, M_5 is inserted between M_4 and M_6 . The output impedances of the conventional and the E-SSF are

$$r_{\text{oB,Conv.}} \approx \frac{1}{g_{m4} \cdot g_{m6} r_{o4}}$$
 (1)

$$r_{\text{oB,Prop.}} \approx \frac{1}{g_{m4} \cdot g_{m6} r_{o4} \cdot g_{m5} r_{o5}},$$
 (2)

respectively. The inserted common-gate amplification stage formed by M_5 reduces the output impedance of the SSF buffer by a factor of $g_{m5}r_{o5}$, and thus provides a larger driving capability.

To reduce chip area, C_1 and C_L are implemented by low-voltage low-leakage MOS capacitors, with the values of 19 and 100 pF, respectively. Additional 1 pF is connected to the gate of the NMOS current mirrors for decoupling. Although M_2 and M_5 need gate bias voltages $V_{\rm B1}$ and $V_{\rm B2}$, their gates can be connected to $V_{\rm MIR}$ to save additional bias branches. This bias sharing configuration is acceptable as both gates of M_2 and M_5 need to be referenced to ground.

Simulation results: The proposed idea is simulated in a 28 nm CMOS process. The AC responses including the Bode plots and the PSR curves with the load current ranging from 0.1 to 10 mA are given in Fig. 3. The loop UGF of the cascode FVF with the E-SSF is 1.28 GHz with 49° phase margin. Benefitting from the UHF bandwidth, full-spectrum PSR is achieved with the worst case of -18.9 dB happening at 1.55 GHz, while the low-frequency PSR is around -27 dB. The supply noise at above 1 MHz from the left part of Fig. 2 is filtered out by C_1 . Thus, the PSR is improved at the 1-100 MHz range. The transient response is shown in Fig. 4. The voltage undershoot and overshoot are 26 and 21 mV, respectively, when the load current changes from 0.1 to 10 mA with the rise-/fall-time $T_{\rm Edge}$ of 30 ps.

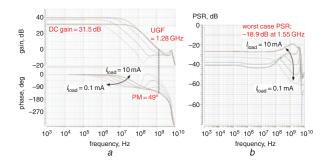


Fig. 3 Simulated AC responses of proposed LDO with load current ranging from 0.1 to 10 mA

- a Bode plot of open-loop transfer function
- b PSR performance of proposed LDO

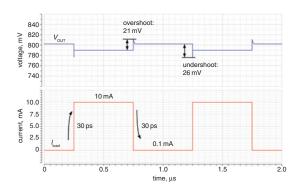


Fig. 4 Simulated load transient response of LDO with 1.0 V input voltage and 0.8 V output voltage with voltage positioning

The performance summary and comparisons with state-of-the-art designs are listed in Table 1. Comparing with [1], this work achieves over 6 dB better worst case PSR and about 70% less $\Delta V_{\rm OUT}$ during the load transient. The figure-of-merit (FOM) equation of speed, as given below, was proposed in [4] and adopted here for comparison

$$FOM = T_{R} \frac{I_{Q}}{I_{MAX}} = \frac{C \times \Delta V_{OUT}}{I_{MAX}} \times \frac{I_{Q}}{I_{MAX}}$$
(3)

Table 1: Performance comparison with state-of-the-art designs

Publication	[4] 2005	[<mark>6</mark>] 2014	[1] 2015	This work
Technology, nm	90	350	65	28
V _{OUT} , V	0.9	1.2	1	0.8
Dropout, mV	300	600	150	200
I_Q	6 mA	44 μΑ	50–90 μΑ	100 μΑ
I _{MAX} , mA	100	12	10	10
Total cap.	600 pF	100 pF	140 pF	120 pF
Worst-case PSR	N/A	-38 dB at 50 MHz	-12 dB at 5 MHz	-18.9 dB at 1.55 GHz
$\Delta V_{ m OUT}$ @ $T_{ m Edge}$	90 mV at 100 ps	105 mV at 500 ns	82 mV at 200 ps	26 mV at 30 ps
$T_{\rm R}^{\rm a}$	0.54 ns	N/A	1.15 ns	312 ps
FOM ^a , ps	32	N/A	5.74	3.12

^aCalculated from T_R and FOM equations proposed in [4].

Conclusion: This Letter reports a fully on-chip FVF-based LDO with an E-SSF designed in a 28 nm CMOS process. The proposed UWB LDO achieves a -18.9 dB worst-case full-spectrum PSR with 200 mV dropout voltage, and obtained an ultra-fast response time of 312 ps and an FOM of 3.12 ps.

Acknowledgments: This work was financially supported by the Macao Science and Technology Development Fund (FDCT) grant no. 122/2014/A3 and Research Committee of University of Macau.

© The Institution of Engineering and Technology 2016 Submitted: *16 May 2016* E-first: *14 July 2016* doi: 10.1049/el.2016.1719

One or more of the Figures in this Letter are available in colour online.

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